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Base materials for printed circuits— Polyimide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)

ICS 31.180

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thermoplastic polymers

Reference number: JIS C 6490: 1998 (E)

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## Foreword

This translation has been made based on the original Japanese Industrial Standard revised by the Minister of International Trade and Industry through deliberations at Japanese Industrial Standards Committee in accordance with the Industrial Standardization Law. Consequently **JIS C** 6490: 1993 is replaced with **JIS** C 6490: 1998.

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In the event of any doubts arising as to the contents, the original JIS is to be the final authority.

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## Base materials for printed circuits— Polyimide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)

Introduction This Japanese Industrial Standard has been prepared based on IEC 60249-2-16 Base materials for printed circuits—Part 2: Specifications—Specification No.16: Polyimide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test) published as the first edition in 1992, Amendment 1 (1993) and Amendment 2 (1994) with some modifications in line with actual conditions in Japan to such items as surface corrosion, corrosion at the edge, etc. Those amendments were edited and compiled into the text.

The portions with dotted underlines show the matters not included in the original International Standard. The **IEC** standard number is based on the new numbering system of **IEC** standards put in force on January 1st, 1997, and the standards published before the said date are numbered by adding 60000 to the former number. This is only the change in the numbering system and the contents remain unchanged.

1 Scope This Standard specifies requirements on polyimide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test), in thickness of 0.5 mm up to 6.4 mm (hereafter referred to as "copper-clad laminates").

Polyimide woven glass fabric laminates are available in two types:

- type 1: modified polyimide resin
- type 2: unmodified polyimide resin

The two types have equal properties except for the glass transition temperature, and this specification therefore differentiates them only in respect of the glass transition temperature.

- Remarks 1 To designate this material, the reference 60249·2·16·FV1·IEC·PI·GC·Cu may be used; if there is no risk of confusion, the type designation may be abbreviated to read IEC·60249·2·16·FV1.
  - 2 The corresponding International Standard is as follows.

IEC 60249-2-16: 1992 Base materials for printed circuits—Part 2: Specifications—Specification No.16: Polyimide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)

2 Normative references The following standards contain provisions which, through reference in this Standard, constitute provisions of this Standard. The most recent editions of the standards indicated below shall be applied.

JIS C 6481 Test methods of copper-clad laminates for printed wiring boards

JIS C 6515 Copper foil for printed wiring boards

Remarks: This standard is identical with IEC 61249-5-1: 1995 Materials for interconnection structures—Part 5: Sectional specification set for con-